



Product Change Notification

Change Notification #: **115901 - 01**
Change Title: **Intel® Xeon® Gold 6144 Processor, PCN 115901-01, Product Design, Order Code, New MM#s and S-specs to Order**
Reason for Revision: Adding Additional Statement to Description
Date of Publication: **December 19, 2017**

Key Characteristics of the Change:

Product Design, Order Code

Forecasted Key Milestones:

Last Product Discontinuance Order Date:	December 13, 2017
Last Product Discontinuance Shipment Date:	January 29, 2018
Date of Samples Availability:	November 10, 2017
Date of Qualification Data Availability:	November 10, 2017
Date of First Availability of Post-Conversion Material:	December 04, 2017
Date Customer Must be Ready to Receive Post-Conversion Material:	January 29, 2018

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Reason for Revision: Adding Additional Statement to Description

Description of Change to the Customer:

In order to ensure a continuous supply of the Intel® Processors listed in the Products Affected/Intel Ordering Codes table below have shifted to other Intel products.

Description of changes between current and replacement MM#/S-Spec:

Replacement processors include updates to ICC max value.

This is not a functional or TDP change. IccIn Max value is being reduced from 228A to 205A to enable max system support for these values

New post-conversion material master numbers (MM#s) and S-specs will be replacing the pre-conversion product data listed in the Products Affected/Intel Ordering Codes table. Pre-conversion product data will not be available to customers after the Last Product Discontinuance Order Date listed in this Product Change Notification

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers, although Intel encourages customers to understand the changes and determine the impact on their applications.

Replacement MM# and S-Specs processors are already available to order and Intel recommends switching to the new MM# and S-Spec replacement parts for future orders.

Please contact your Intel Field Sales Representative with any questions, requests or concerns.

Products Affected / Intel Ordering Codes:

Pre-Conversion Product Data						Post-Conversion Product Data			
Marketing Name	Frequency	Stepping	Product Code	S-Spec	MM#	Product Code	S-Spec	MM#	Stepping
Intel® Xeon® Gold 6144 Processor	3.5 GHZ	H0	CD8067303657302	S R3MB	959504	CD8067303843000	S R3TR	962201	H0

PCN Revision History:

Date of Revision:

November 10, 2017

December 19, 2017**Revision Number:**

00

01**Reason:**

Originally Published PCN

Adding Additional Statement to Description



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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